

IEEE 802.3 400 Gb/s/Lane Signaling Study Group meeting

July 2026 Plenary Hybrid Meeting

Montreal, Canada

Meeting minutes prepared by Beth Kochuparambil

July 15, 2026

Kent Lusted as IEEE 802.3 400 Gb/s/lane Study Group Chair called the meeting to order at 8:00am (EDT)

Presentation #1 Agenda and General Information

Presenter: Kent Lusted

https://www.ieee802.org/3/400GPL/public/2607/agenda_400GPL_01_2607.pdf

The Chair reminded participants to declare their affiliation in the online meeting tool. Failure to do so would result in expulsion from the meeting. He also reminded participants that registration is required for this meeting.

The Chair stated that attendance will be taken via IMAT and noted that it counted towards IEEE 802.3 Working Group voting membership and provided the link to mark one's attendance.

The Chair asked if there were any modifications to the agenda (see slide #4) . He noted that P802.3dj needed more time for comment resolution, P802.3dj would begin at the start of AM2 if the Study Group finished business early. There were no modifications requested. There were no objections. Agenda approved.

The Chair pointed to the minutes from a recent Study Group Electronic Interims (see slide #5) stating that he, nor Kochuparambil, received feedback on the minutes, and none brought up on the floor. The Chair asked if there was opposition to approving the minutes. No one objected. Minutes approved

The Chair reminded participants to follow the meeting decorum rules. The Chair asked for members of the press to identify themselves. No one identified as such.

The Chair expressed the goals for the meeting (see slide #11).

The Chair presented the second slide of the IEEE SA Pre-PAR Patent Policy slides (see slide #24). He did a call for Potentially Essential Patents, and no one came forward.

The Chair presented the third slide of the IEEE SA Copyright Policy slides (see slide #26). He noted – “By participating in this activity, you agree to comply with the IEEE Code of Ethics, all applicable laws, and all IEEE policies and procedures including, but not limited to, the IEEE SA Copyright Policy.”

The Chair reminded participants of the IEEE Code of Ethics and Conduct (see slide #28). He noted “All participants in IEEE-SA activities are expected to adhere to the core principles underlying the IEEE Code of Ethics and IEEE Code of Conduct”.

The Chair presented the second slide (see slide #29) of the IEEE SA Participation Policy slides. The Chair noted – “Participants in the IEEE-SA “individual process” shall act independently of others, including employers. By participating in standards activities using the “individual process”, you are deemed to accept these requirements; if you are unable to satisfy these requirements then you shall immediately cease any participation.”

The Chair presented the third slide (see slide #30) of the IEEE SA Participation Policy. Chair noted that IEEE-SA standards activities should allow the fair & equitable consideration of all viewpoints, and The IEEE-SA Standards Board Bylaws (clause 5.2.1.3) specifies that “the standards development process shall not be dominated by any single interest category, individual, or organization”.

The Chair noted the IEEE Ethics Reporting Line (see slide #32) to the participants.

The Chair asked if any clarification was needed on IEEE SA Policies. There was none.

The Chair reminded participants to declare their affiliation in the online meeting tool. Failure to do so would result in expulsion from the meeting.

Presentation #2 Summary of Comments Received Against P802.3dv Project Documentation and Proposed Responses

Presenter: Beth Kochuparambil

https://www.ieee802.org/3/400GPL/public/2607/lusted_400GPL_01a_2607.pdf

The Chair prefaced the study group, noting the 8 received comments from the IEEE 802 community and explained the process.

Edits were made live and update posted after the meeting.

Motion #1

Move to adopt slides 5 to 12 of lusted_400GPL_01a_2607 as the responses to the comments received against the IEEE P802.3dv project documentation.

M: Mike Dudek

S: Jim Weaver

The motion was ruled technical and required $\geq 75\%$ to pass

No discussion on the motion.

Passed by unanimous consent at 8:34am

The Chair explained the next steps with the PAR and CSD edits and approvals.

Motion #2

Move to request that IEEE 802.3 WG request the rechartering of the 400 Gb/s/lane Signaling Study Group.

M: Jim Weaver

S: John D'Ambrosia

The motion, by rule, required $\geq 50\%$ to pass

No discussion on the motion.

Passed by unanimous consent at 8:36am

The Chair gave closing announcements

- Slide 27 of Presentation 1 was shown
- Reminded participants of the 3 upcoming Electronic Teleconference Meetings
- Gratitude expressed to participants who were willing to defer the technical discussions to the electronic teleconferences

The Chair noted that the agenda was complete. Meeting adjourned at 8:42am ET

Attendance

Name	Employer	Affiliation
Abramczyk, Jaroslaw		Coherent
Ahuja, Ramanjit	ON Semiconductor	ON Semiconductor
Akinwale, Oluwafemi	Intel Corporation	Intel Corporation
Alloin, Laurent		Ciena Corporation
Alwishah, Abbas	Molex Incorporated	Molex Incorporated
Baek, Brian		Apple Inc.
Ben-Artzi, Liav	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
Bernier, Eric	Huawei Technologies Canada Co., Ltd.	Huawei Technologies Canada Co., Ltd.
Brillhart, Theodore	Fluke Corporation	Fluke Corporation
Brooks, Paul	Viavi solutions GmbH	Viavi Solutions
Brown, Matthew	Alphawave Semi	Qualcomm
Bruckman, Leon	NVIDIA	NVIDIA
Calvin, John	Keysight Technologies	Keysight Technologies
Castro, Jose	Panduit	Panduit Corp.
Chang, Jae-yong	Keysight Technologies Inc	Keysight Technologies Inc
Chang, Yongmao	Inphi Corporation	Source Photonics
Chen, Chan	Self Employed	Independent/AOI
cheng, xiaoyue		Infineon Technologies
Choudhury, Golam	Genuine Optics	Genuine Optics
Chow, Kai Soon		Apple Inc.
Chughtai, Muhammad Saad		Tektronix, Inc.

Cole, Christopher R	Finisar Corporation	Coherent Corp.
Cordaro, Joseph	Infineon Technologies	Infineon Technologies
D'Ambrosia, John	Futurewei Technologies, U.S. Subsidiary of Huawei	Futurewei Technologies, U.S. Subsidiary of Huawei
Dai, Shaoan		Infineon Technologies
Dar, Marva	TE Connectivity	TE Connectivity
Dawe, Piers J G	NVIDIA	Nvidia
de Koos, Andras	Microchip Technology Inc	Microchip Technology Inc
Djahanshahi, Hormoz	Microchip Technology, Inc.	Microchip Technology, Inc.
Donahue, Curtis	Rohde & Schwarz	Rohde & Schwarz
Dsilva, Hansel		Amphenol Corporation
Dudek, Michael	Marvell	Marvell
Estes, David	Spirent Communications	VIAVI Solutions
Estrakh, Daniel	Valens Semiconductor	Valens Semiconductor
Ferretti, Vincent	Corning Incorporated	Corning Incorporated
Galan, Jose	MaxLinear, Inc.	MaxLinear, Inc.
Gareau, Sebastien		Ciena Corporation
Gauthier, Claude	NXP Semiconductors	NXP Semiconductors
Geng, Limin	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Ghiasi, Ali	Ghiasi Quantum LLC	Ghiasi Quantum LLC; Marvell Semiconductor, Inc.
Goel, Sachin	Aviva Links Inc	NXP
Gorshe, Steven Scott	Microchip Technology, Inc.	Microchip Technology, Inc.
Hamilton, Mark	Cadence Design Systems	Cadence Design Systems
Han, Ruibo	China Mobile Communications Corporation (CMCC)	China Mobile Communications Corporation (CMCC)

Hand, Steven		Nokia
HE, MICHAEL	TeraHop Pte. Ltd.	TeraHop Pte. Ltd.
He, Xiang	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Healey, Adam	Broadcom Inc.	Broadcom Inc.
Heck, Howard	TE Connectivity	TE Connectivity
Helely, Oren		Marvell Semiconductor, Inc.
Hiroaki, Kukita	Yamaichi Electronics	Yamaichi Electronics
Holdrege, Matthew	Microchip Technology, Inc.	Microchip Technology, Inc.
Hon, Kam Yan		Cisco Systems, Inc.
Houck, TJ	Infineon Technologies	Infineon Technologies
Hu, Runlong		China Mobile Communications Group Co.,Ltd; China Mobile Communications Group Co.,Ltd
Huang, Kechao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Huber, Thomas	Nokia	Nokia
Hutchison, Guy	Aviva Links	NXP Semiconductors
HYAKUTAKE, YASUHIRO	Orbray Co., Ltd.	Orbray Co., Ltd.
Irwin, Scott	MoSys, Inc.	ADTRAN Inc.
Isono, Hideki	Furukawa FTEL Optical Components Limited	Furukawa FTEL Optical Components
Issenhuth, Tom	Issenhuth Consulting, LLC	Huawei Technologies Co., Ltd
Iwasaki, Yutaka	Hirose Electric Co.,Ltd.	Hirose Electric Co., Ltd.
Jackson, Kenneth	Sumitomo Electric Industries, LTD	Sumitomo Electric Industries, LTD
Jin, Robert	Montage Technology, Inc	Montage Technology
Johnson, John	Broadcom Corporation	Broadcom Corporation

Kagami, Manabu	Nagoya Institute of Technology	Nagoya Institute of Technology (NITech)
Kareti, Upen	Cisco Systems, Inc.	Cisco Systems, Inc.
KATO, TAKAHIRTO	Dexerials	Dexerials
Kimber, Eric	Semtech Ltd	Semtech Ltd
Kochuparambil, Elizabeth	Cisco Systems, Inc.	Cisco Systems, Inc.
Kocsis, Sam	Amphenol Corporation	Amphenol Corporation
Kondo, Taiji	Dexerials Corporation	Dexerials Corporation
Kota, Kishore	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
Kutscher, Noam	Marvell Semiconductor, Inc.	Marvell
Landry, Gary	Coherent Corp.	Coherent
Lasry, Ariel	Qualcomm Technologies, Inc	Qualcomm Technologies, Inc
Law, Andrew	Student	Self
Law, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Lee, Sylvanus	Leviton Manufacturing Co.	Leviton Manufacturing Co.
Lessard, Stephane	Ericsson AB	Ericsson AB
Lewis, David	SPECIPHY / Lumentum	SPECIPHY, LUMENTUM
Li, Mike-Peng	Altera Corporation	Intel Corporation
Li, Pei-Rong	MediaTek Inc.	MediaTek Inc.
Little, Terrance	Foxconn Electronics Inc.	Foxconn Electronics Inc.
Liu, Cathy	Broadcom Corporation	Broadcom Corporation
Lo, William	Axonne Inc.	Axonne Inc.
Long, Richard	TE Connectivity	TE Connectivity
Iu, chao	BMW Group	BMW Group

Lusted, Kent	Synopsys, Inc.	Synopsys, Inc.
Lyu, Yunping(Lily)	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Maki, Jeffery	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Maniloff, Eric	Ciena Corporation	Ciena Corporation
Marques, Flavio	Lightera	Lightera
Mascitto, Marco	Nokia Canada Inc.	Nokia
Matuz, Balazs		Huawei Technologies Duesseldorf GmbH
Mazzini, Marco	Cisco Systems, Inc.	Cisco Systems, Inc.
Mellitz, Richard	Samtec, Inc.	Samtec, Inc.
Moorwood, Charles	Keysight Technologies	Keysight Technologies
Muller, Shimon	Enfabrica Corp.	Enfabrica
Muma, Scott	Microchip Technology, Inc.	Microchip Technology, Inc.
MURAKAMI, YUKI	1Finity	1Finity
Murty, Ramana	Broadcom Inc.	Broadcom Corporation
Nicholl, Gary	Cisco Systems, Inc.	Cisco Systems, Inc.
Nicholl, Shawn	Advanced Micro Devices (AMD)	Advanced Micro Devices (AMD)
Ninomiya, Tiger	Accelink USA Corporation	Accelink / Self
Noujeim, Leesa	Google	Google
Nowell, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
Ofelt, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Omori, Kumi	NEC Corporation	NEC Corporation
Opsasnick, Eugene	Broadcom Inc.	Broadcom Inc.
Osorio, Luz	Nokia Canada Inc.	Nokia
Pal, Debajyoti		ON Semiconductor

Palkert, Thomas	Samtec, Inc.	Samtec, Inc.
Parthasarathy, Vasu	Broadcom Corporation	Broadcom Corporation
Pepper, Gerald	Keysight Technologies	Keysight Technologies
Perez De Aranda Alonso, Ruben	Knowledge Development for POF SL	Cisco Systems, Inc.
Rabinovich, Rick	Keysight Technologies	Keysight Technologies
Ransford, Michael		Corning Incorporated
Razavi, Alireza	Marvell	Eliyan
Ren, Hao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Rodes, Roberto	II-VI	II-VI
Rysin, Alexander	NVIDIA	NVIDIA
Sakai, Toshiaki	Socionext Inc.	socionext
Sambasivan, Sam	AT&T	AT&T
Shah, Anup	Siemens Corporation	Siemens EDA
Shakiba, Mohammad	Huawei Technologies Canada Co., Ltd.	Huawei Technologies Canada; Huawei Technologies Co., Ltd
Sharon, Ari		Terawand
Shoval, Ayal	Synopsys, Inc.	Synopsys, Inc.
Shrikhande, Kapil	Marvell Semiconductor, Inc.	Upscale AI
Shukla, Priyank	Synopsys, Inc.	Synopsys, Inc.
Sikkink, Mark	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Simms, William	NVIDIA Corporation	NVIDIA Corporation
Slavick, Jeff	Broadcom Inc	Broadcom Inc
Sommers, Scott	Molex LLC	Molex Incorporated
Son, Yung Sung	Optomind Inc	Optomind Inc

Sorbara, Massimo	GLOBALFOUNDRIES	GLOBALFOUNDRIES
Srivastava, Atul	NEL-America	NTT Electronics
Sun, Wensheng	Credo Semiconductor	Credo Semiconductor
Sun, Yi	Lightera	Lightera
Swenson, Norman	Norman Swenson Consulting	Norman Swenson Consulting; Point2 Technology Inc.; Nokia
TAKAHARA, TOMOO	FUJITSU LABORATORIES LIMITED	1FINITY
Tan, Kan	Tektronix, Inc.	Tektronix, Inc.
Tan, Yuxuan	Motorcomm	Motorcomm
Tanc, Ahmet		NXP Semiconductors; NXP Semiconductors
Tanz, Simon		BMW AG; BMW Group
Tartaglia, Antonio	Ericsson AB	Ericsson AB
TAZEBAY, MEHMET	Broadcom Corporation	Broadcom Corporation
Theodoras, James	Scintil Photonics	Scintil Photonics
Tooyserkani, Pirooz	Cisco Systems, Inc.	Cisco Systems, Inc.
Tracy, Nathan	TE Connectivity	TE Connectivity
Tran, Viet	Keysight Technologies	Keysight Technologies
Vakilian, Kambiz	Broadcom Corporation	Broadcom Corporation
van Dyck, Peter	Infineon Technologies	Infineon Technologies
Veloso Cauce, Gumersindo	BMW Group	BMW AG; BMW Group
Wang, Haojie	China Mobile Communications Corporation (CMCC)	China Mobile Communications Corporation (CMCC)
Wang, Tongtong	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Wang, Xiaofeng	Qualcomm Incorporated	Qualcomm Incorporated

WANG, Xuebo	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Weaver, James	Arista Networks	Arista Networks
Welch, Brian	Cisco Systems, Inc.	Luxtera
Wig, Timothy	Samtec, Inc.	Samtec, Inc.
Wingrove, Michael	Ciena Corporation	Ciena Corporation
Wu, Peter	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
XU, LI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Xu, Yu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Yamazaki, Kinya	APRESIA Systems	APRESIA Systems
Yin, Shuang		Google
Zhang, Tingting	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Zhuang, Shu		Anritsu Company
Zhuang, Yan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Zivny, Pavel	Lumilens	Lumilens
Zou, Congshi	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd